

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3	semiconductor and dielectric and (copper same ((chemical adj mechanical adj polishing) or CMP)) and (copper same ((electro adj polishing) or electropolishing)) and (plasma adj etch)	USPAT	ADJ	ON	2004/12/06 14:28
L2	2	semiconductor and dielectric and (copper same ((chemical adj mechanical adj polishing) or CMP)) and (copper same ((electro adj polishing) or electropolishing)) and (plasma adj etch)	US-PGPUB	ADJ	ON	2004/12/06 14:30
L3	0	semiconductor and dielectric and (copper same ((chemical adj mechanical adj polishing) or CMP)) and (copper same ((electro adj polishing) or electropolishing)) and (plasma adj etch)	EPO	ADJ	ON	2004/12/06 14:30
L4	0	semiconductor and dielectric and (copper same ((chemical adj mechanical adj polishing) or CMP)) and (copper same ((electro adj polishing) or electropolishing)) and (plasma adj etch)	JPO	ADJ	ON	2004/12/06 14:30
L5	0	semiconductor and dielectric and (copper same ((chemical adj mechanical adj polishing) or CMP)) and (copper same ((electro adj polishing) or electropolishing)) and (plasma adj etch)	IBM_TDB	ADJ	ON	2004/12/06 14:30
L6	0	semiconductor and dielectric and (copper same ((chemical adj mechanical adj polishing) or CMP)) and (copper same ((electro adj polishing) or electropolishing)) and (plasma adj etch)	DERWENT	ADJ	ON	2004/12/06 14:30